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Title: JP61078592A2: SILVER SOLDER MATERIAL

Country: JP Japan

Kind: A

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TOKURIKI HONTEN CO LTD  
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Priority Number: 1984-09-25 JP1984000198614

Abstract:

PURPOSE: To obtain a titled material which is excellent in corrosion resistance at the time of use and in a post-treatment process, and also to hold it in sufficient spreading property and wettability by forming a solder material by adding Ge, Pd and Li of a specified quantity to Ag.

CONSTITUTION: A silver solder material is constituted of 0.05W19% Ge, 0.01W10% Pd, 0.01W2% Li, and Ag as a balance. Also, by adding one kind or two kinds or more of Fe, Co and Ni to an Ag-Ge-Pd-Li compound alloy, in case when a base metal of Fe, Co and Ni, and their alloy, for instance, 42 Fe-Ni, covar, stainless steel, etc. has been soldered, the metallic organization is fined and also the soldering strength is improved.

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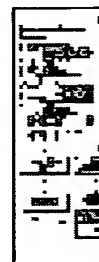
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